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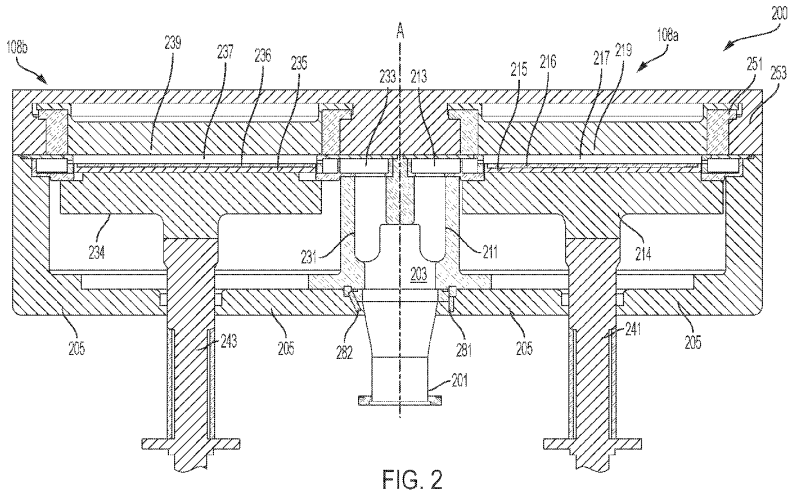


FIG. 2

(57) Abstract: In one embodiment, a processing system for semiconductor manufacturing, includes a chamber housing, a first process chamber, a second process chamber and a foreline disposed in the chamber housing and between the first process chamber and the second process chamber. The first and second process chambers are in the chamber housing and each includes a pump ring and a liner. The pump ring includes a port and baffle. The pump rings and liners each partially define a first and second process volume respectively. The foreline includes a first exhaust chamber fluidly coupled to the first process volume and a second exhaust chamber fluidly coupled to the second process volume.

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